

# Lightweight Thermal Management Strategies for the Silicon Detectors of CBM at FAIR

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## **CBM-FAIR & Its Silicon-Based Inner Tracker**

Fixed-target heavy-ion collision experiment to study strongly interacting matter at neutron star core densities

- $\leq 10^7$  reactions/s at  $\sqrt{s_{NN}} = 2.9 4.9$  GeV
- Determination of vertices ( $\sigma \approx 50 \ \mu m$ )
- Identification of leptons and hadrons
- Di-electron and muon setup
- Fast and radiation hard detectors
- Trigger-less free-streaming readout
- Online event selection
- 4-D event reconstruction
- 4 planar layers, z = 8 20 cm (in vacuum)  $\approx$  0.15 m<sup>2</sup> area, 288 sensors, 150M pixels CMOS MAPS (MIMOSIS; TowerJazz 180 nm)  $\approx 0.3\% - 0.5\%$  X<sub>o</sub> per layer  $\sigma_{xy}$  = 5 µm,  $\sigma_z$  = 70 µm,  $t_{frame}$  = 5 µs
  - $< 0.7 \times 10^{14} n_{eq}/cm^2$ , 5 MRad < 80 MHz/cm<sup>2</sup>; 0.1 MHz reactions

Micro-Vertex Detector (MVD)

	Silicon Tracking System (STS)
	8 planar layers, $z = 30 - 100$ cm (in air)
	pprox 4m <sup>2</sup> area, 876 sensors, 1.8M channels
)	Double-Side Strips (Hamamatsu w/ SMX)
	pprox 0.3% – 2% X <sub>0</sub> per layer
	$\sigma_{xy}$ = 25 $\mu$ m, $\sigma_t$ = 5 ns
	$< 1 \times 10^{14}  n_{\rm eq}^{2}$
	< 10 MHz/cm <sup>2</sup> ; 10 MHz reactions

n field of a superconducting dipole magnet (1 T·m), azimuthal acceptance of 2.5 – 25°

Lightweight, large-area, fast, radiation hard silicon detectors deployed for vertex (MAPS-based) and track (strip-based) reconstruction

### **Thermal Management Strategies**

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Swaqelok

MVD: Liquid-assisted conductive cooling

STS: Liquid-assisted impinging air-jet cooling

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Cross-Sectional View (Illustration) of the MVD Quadrant

- Temperature: ~ 0 °C, down to -20 °C
- Power: 50 100 mW/cm<sup>2</sup>, ~ 200 W total
- Liquid-cooled Heat Sink
  - Outside physics acceptance
  - Monophase 3M<sup>™</sup> NOVEC<sup>™</sup> 649 ≥ -20 °C
  - Vacuum-brazed aluminium heat sink
- Sensors passively cooled via Thermal Pyrolytic Graphite (TPG) carriers
  - Thermally Conductive ( $\lambda > 1500 \text{ W/m} \cdot \text{K}$ )

*Full-scale MVD Quadrant* 

 $(191.0 \times 170.4 \text{ cm}^2)$ 

- Low material budget ( $X_0 = 19.3$  cm)
- Polishing, laser ablation cutting, hatching Parylene coating, plasma activation



STS-Module: Silicon Sensors  $(6.2 \times 6.2 \text{ cm}^2)$  + Microcables (Shielded) + FEE-Boards (10×3 cm<sup>2</sup>, 25 W)

- Temperature: ~ +10 °C
- Silicon Sensors
  - Power: 50 mW/cm<sup>2</sup> at +10 °C, EOL
  - Impinging air-jets via perforated CF tubes
- Front-End Electronics
  - Outside physics acceptance (40 kW in 3 m<sup>3</sup>)
  - Monophase 3M<sup>™</sup> NOVEC<sup>™</sup> 649 @ -20 °C
  - Friction-stir welded aluminium plates
  - Thermally conductive heat path



"Lighter" air cooling for silicon sensors

*"Heavier" liquid cooling for FEE* (milled channels)

#### **Experimental Validation with Realistic Demonstrators**

Operational parameters and margins studied with thermal demonstrators under realistic conditions

1T (K)

8.7 8.3 7.9 7.5 7.2 6.8

6.4 6.0

5.7 5.3 4.9 4.5

3.4 3.0 2.6 2.3

P = 15 W

MVD Observable: Temperature gradient in the TPG bulk ( $\Delta T$ )



#### Experimental Setup (MVD Test Stand @ Uni. Frankfurt)



STS Observable: Thermal runaway behavior at EOL fluence



Experimental Setup (Thermal Demonstrator @ GSI)









- Vacuum and cooling test stand for MVD quadrants
- Pre-series cooling element prototypes
- Exploration of operational parameters
- Substantial safety margins
- Agreement with quadrant-level thermal FEA simulations ( $\Delta T$  in TPG bulk)

Thermal FEA Simulations

- Simulations:  $\Delta T = 5.0 \text{ K}$
- Experiment at -30°C: ΔT = 6.7 K
- Experiment at +20°C:  $\Delta T = 4.9 \text{ K}$
- Thermal Demonstrator to experimentally Temperature hotspots ∝ fluence verify the sensor and FEE cooling concept
- Pre-series cooling element prototypes
- Exploration of operational parameters
- Substantial margins at EOL fluence



Bundesministerium für Bildung

und Forschung

(outer ladders)

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Detector mechanics: Design finalized. First-of-series production: Starting soon. CBM global commissioning in 2028.

- References
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